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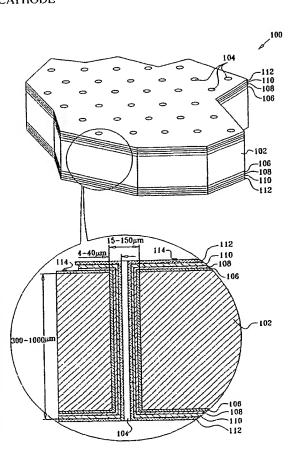
- (71) Applicant (for all designated States except US): TEL-AVIV UNIVERSITY FUTURE TECHNOLOGY DEVELOPMENT L.P. [IL/IL]; P.O. Box 39040, 69978 Tel-Aviv (IL).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): NATHAN, Menachem [IL/IL]; 5 Arie Suslik Street, Tel Aviv 69359 (IL).

PELED, Emanuel [IL/IL]; 25 Hanote'a Street, 40500 Even Yehuda (IL). GOLODNITSKY, Diana [IL/IL]; 16/6 Hanagid Street, 75482 Rishon Letzion (IL). YUFIT, Vladimir [IL/IL]; 14/19 Michashvili Street, 77535 Ashdod (IL).

- (74) Agents: SANFORD T. COLB & CO. et al.; P.O. Box 2273, 76122 Rehovot (IL).
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(54) Title: THIN-FILM CATHODE FOR 3-DIMENSIONAL MICROBATTERY AND METHOD FOR PREPARING SUCH CATHODE



(57) Abstract: A method for producing a microbattery including providing a conductive substrate, forming a thin film cathodic layer on at least one surface of the conductive substrate, subsequently forming a thin film electrolyte layer over the cathodic layer and subsequently forming a thin film anodic layer over the electrolyte layer.

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